			,	
•	Member of the Texas Instruments <i>Widebus</i> ™ Family	DGG	, DGV, OR (TOP)	DL PACKAGE VIEW)
٠	<i>EPIC</i> [™] (Enhanced-Performance Implanted CMOS) Submicron Process		DE [1 Y1 [2	56 CLK
•	Checks Parity		Y2 3	54 11A/YERREN
•	Able to Cascade With a Second			53 GND
	SN74ALVCH16903		Y1 5	52 11Y1
•	ESD Protection Exceeds 2000 V Per		Y2 6	51 🛛 11Y2
	MIL-STD-883, Method 3015; Exceeds 200 V	V		50 🛛 V _{CC}
	Using Machine Model (C = 200 pF, R = 0)	3`	Y1 🛛 8	49 2A
•	Latch-Up Performance Exceeds 250 mA Per		Y2 🛛 9	48 🛛 3A
	JESD 17		Y1 10	47 4 A
•	Bus Hold on Data Inputs Eliminates the		ND [11	46 GND
	Need for External Pullup/Pulldown		Y2 12	45 12A
	Resistors	-	Y1 13 Y2 14	44 12Y1 43 12Y2
•	Package Options Include Plastic 300-mil		Y2 U 14 Y1 U 15	43 1 12 Y 2 42 5A
	Shrink Small-Outline (DL), Thin Shrink	-	Y2 16	42 0 5A 41 0 6A
	Small-Outline (DGG), and Thin Very		Y1 17	40 7A
	Small-Outline (DGV) Packages			39 GND
	vintion		Y2 🛛 19	38 APAR
aesc	ription	8'	Y1 20	37 🛛 8A
	This 12-bit universal bus driver is designed for	8`	Y2 🛛 21	36 J YERR
	2.3-V to 3.6-V V _{CC} operation.	V	CC 22	35 🛛 V _{CC}
	The SN74ALVCH16903 has dual outputs and can		Y1 23	34 9 A
	operate as a buffer or an edge-triggered register.		Y2 24	33 MODE
	In both modes, parity is checked on APAR, which		ND 25	32 GND
	arrives one cycle after the data to which it applies.		Y1 26	
	The YERR output, which is produced one cycle		Y2 27 DE 28	30 PARI/O 29 CLKEN
	after APAR, is open drain.	PARC	/⊏ Ц∠⁰	29 UCLKEN

MODE selects one of the two data paths. When MODE is low, the device operates as an edge-triggered register. On the positive transition of the clock (CLK) input and when the clock-enable (CLKEN) input is low, data set up at the A inputs is stored in the internal registers. On the positive transition of CLK and when CLKEN is high, only data set up at the 9A–12A inputs is stored in their internal registers. When MODE is high, the device operates as a buffer and data at the A inputs passes directly to the outputs. 11A/YERREN serves a dual purpose; it acts as a normal data bit and also enables YERR data to be clocked into the YERR output register.

When used as a single device, parity output enable (PAROE) must be tied high; when parity input/output (PARI/O) is low, even parity is selected and when PARI/O is high, odd parity is selected. When used in pairs and PAROE is low, the parity sum is output on PARI/O for cascading to the second SN74ALVCH16903. When used in pairs and PAROE is high, PARI/O accepts a partial parity sum from the first SN74ALVCH16903.

A buffered output-enable (\overline{OE}) input can be used to place the 24 outputs and \overline{YERR} in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.



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description (continued)

OE does not affect the internal operation of the device. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16903 is characterized for operation from 0°C to 70°C.

Function Tables

			FUI	NCTION				
		INPUTS			OUTPUTS			
OE	MODE	CLKEN	CLK	Α	1Y _n †–8Y _n †	9Yn [†] - 12Yn [†]		
L	L	L	Ŷ	Н	Н	н		
L	L	L	\uparrow	L	L	L		
L	L	Н	\uparrow	Н	Y ₀	н		
L	L	Н	\uparrow	L	Y ₀	L		
L	Н	Х	Х	Н	н	н		
L	Н	Х	Х	L	L	L		
н	Х	Х	Х	Х	Z	Z		

1n = 1, 2

PARITY FUNCTION

		INP	UTS			
OE	PAROE [‡]	11A/YERREN§	PARI/O	Σ OF INPUTS 1A – 10A = H	APAR	OUTPUT YERR
L	Н	L	L	0, 2, 4, 6, 8, 10	L	Н
L	Н	L	L	1, 3, 5, 7, 9	L	L
L	Н	L	L	0, 2, 4, 6, 8, 10	Н	L
L	Н	L	L	1, 3, 5, 7, 9	Н	Н
L	Н	L	Н	0, 2, 4, 6, 8, 10	L	L
L	Н	L	Н	1, 3, 5, 7, 9	L	н
L	Н	L	Н	0, 2, 4, 6, 8, 10	Н	н
L	Н	L	Н	1, 3, 5, 7, 9	Н	L
Н	Х	Х	Х	Х	Х	Н
L	Х	Н	Х	Х	Х	Н

[‡]When used as a single device, PAROE must be tied high.

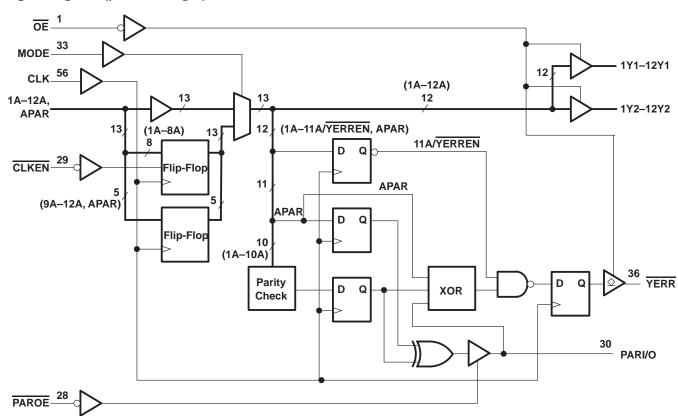
§ Valid after appropriate number of clock pulses have set internal register



Function Tables (Continued)

	PARI/O FUNC	тіон†			
	INPUTS		OUTPUT		
PAROE	1A – 10A = H				
L 0, 2, 4, 6, 8, 10		L	L		
L	1, 3, 5, 7, 9	L	Н		
L	0, 2, 4, 6, 8, 10	Н	Н		
L	1, 3, 5, 7, 9	Н	L		
н	Х	Х	Z		

[†] This table applies to the first device of a cascaded pair of ALVCH16903 devices.



logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Output voltage range, V_O (see Notes 1 and 2) Input clamp current, I_{IK} ($V_I < 0$) Output clamp current, I_{OK} ($V_O < 0$) Continuous output current, I_O Continuous current through each V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 3): DGG package	$\begin{array}{c} -0.5 \text{ V to } 4.6 \text{ V} \\ -0.5 \text{ V to } \text{V}_{CC} + 0.5 \text{ V} \\ -50 \text{ mA} \\ -50 \text{ mA} \\ \pm50 \text{ mA} \\ \pm100 \text{ mA} \\ 81^{\circ}\text{C/W} \end{array}$
DGV package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. This value is limited to 4.6 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

				MIN	MAX	UNIT
Vcc	Supply voltage			2.3	3.6	V
VIH	High-level input voltage	$V_{CC} = 2.3 V to$	2.7 V	1.7		V
VIН	righ-level liput voltage	$V_{CC} = 2.7 V tc$	3.6 V	2		v
VIL	Low-level input voltage	$V_{CC} = 2.3 V to$	2.7 V		0.7	V
_ vi∟		$V_{CC} = 2.7 V tc$	$V_{CC} = 2.7 V \text{ to } 3.6 V$			v
VI	Input voltage			0	VCC	V
VO	Output voltage			0	VCC	V
	High-level output current	$V_{CC} = 2.3 V$	Y port		-12	mA
ЮН		$V_{CC} = 2.7 V$	1 poir		-12	
"OH		V _{CC} = 3 V	PARI/O		-12	
		*:::=:::	Y port		-24	
		V _{CC} = 2.3 V	Y port		12	
		$V_{CC} = 2.7 V$	1 poir		12	
IOL	Low-level output current		PARI/O		12	mA
		$V_{CC} = 3 V$	Y port		24	
			YERR output		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			0	10	ns/V
ТА	Operating free-air temperature			0	70	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PA	RAMETER	TEST	CONDITIONS	VCC	MIN	TYP†	MAX	UNIT	
		I _{OH} = -100 μA		2.3 V to 3.6 V	V _{CC} -0.	2			
		I _{OH} = -6 mA,	V _{IH} = 1.7 V	2.3 V	2				
	Vnort		V _{IH} = 1.7 V	2.3 V	1.7				
VOH	Y port	I _{OH} = -12 mA	V _{IH} = 2 V	2.7 V	2.2			V	
			VIH = 2 V	3 V	2.4				
		I _{OH} = -24 mA,	V _{IH} = 2 V	3 V	2				
	PARI/O	I _{OH} = -12 mA,	V _{IH} = 2 V	3 V	2				
		I _{OL} = 100 μA		2.3 V to 3.6 V			0.2		
		I _{OL} = 6 mA,	V _{IL} = 0.7 V	2.3 V			0.4		
	Y port	I _{OL} = 12 mA	V _{IL} = 0.7 V	2.3 V			0.7		
VOL		IOT = 12 IUX	V _{IL} = 0.8 V	2.7 V			0.4	V	
		I _{OL} = 24 mA,	V _{IL} = 0.8 V	3 V			0.55		
	PARI/O	I _{OL} = 12 mA,	V _{IL} = 0.8 V	3 V			0.55		
	YERR output	I _{OL} = 24 mA		3 V			0.5		
Ц		$V_I = V_{CC}$ or GND		3.6 V			±5	μA	
		V _I = 0.7 V		2.3 V	45				
		V _I = 1.7 V		2.3 V	-45				
II(hold))	V _I = 0.8 V		3 V	75			μΑ	
		V ₁ = 2 V		3 V	-75				
		$V_{I} = 0$ to 3.6 V [‡]		3.6 V			±500		
IOH	YERR output	AO = ACC		0 to 3.6 V			±10	μA	
Ioz§		$V_{O} = V_{CC}$ or GND		3.6 V			±10	μA	
ICC		$V_{I} = V_{CC}$ or GND,	I _O = 0	3.6 V			40	μA	
∆ICC		One input at V _{CC} –0.6 V,	Other inputs at V_{CC} or GND	3 V to 3.6 V			750	μA	
Ci	Control inputs	$V_{I} = V_{CC}$ or GND		3.3 V		5.5		pF	
<u> </u>	Data inputs			3.3 V		5.5		- Pr	
0	YERR output			3.3 V		5		pF	
Co	Data outputs	$V_{O} = V_{CC} \text{ or } GND$		3.3 V		6		р г	
Cio	PARI/O	$V_{O} = V_{CC}$ or GND		3.3 V		7		pF	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. [‡] This is the bus-hold maximum dynamic current required to switch the input from one state to another.

§ For I/O ports, the parameter IOZ includes the input leakage current.



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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figures 1 and 4)

				V _{CC} = ± 0.		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency				125		125		125	MHz
tw	Pulse duration, CLK	\uparrow		3		3		3		ns
		1A–12A before CLK↑	Register mode	1.7		1.9		1.45		
		1A–10A before CLK↑	Buffer mode	5.9		5.2		4.4		
		APAR before CLK [↑]	Register mode	1.2		1.5		1.3		
t _{su}	Setup time		Buffer mode	4.6		3.6		3.1		ns
		PARI/O before CLK↑	Both modes	2.4		2		1.7		
		11A/YERREN before CLK↑	Buffer mode	2		1.9		1.6		
		CLKEN before CLK1	Register mode	2.5		2.6		2.2		
		1A–12A after CLK↑	Register mode	0.4		0.25		0.55		
		1A–10A after CLK↑	Buffer mode	0.25		0.25		0.25		
			Register mode	0.7		0.4		0.7		
	Hold time	APAR after CLK↑	Buffer mode	0.25		0.25		0.25		
th	Hold lime		Register mode	0.25		0.25		0.4		ns
		PARI/O after CLK↑	Buffer mode	0.25		0.25		0.5		
		11A/YERREN after CLK↑	Buffer mode	0.25		0.25		0.4		1
		CLKEN after CLK↑	Register mode	0.25		0.5		0.4		

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 and 4)

PA	RAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CC} = 2.5 V ± 0.2 V		2.7 V	= ۷ _{CC} ± 0.3		UNIT	
		(INFOT)	(001F01)	MIN	MAX	MIN	MAX	MIN	MAX		
f _{max}				125		125		125		MHz	
	Buffer mode	А	Y	1	4.4		4.2	1.1	3.8		
^t pd	Deth medee	CLK	YERR	1	5.7		4.9	1.4	4.4	ns	
	Both modes	CLK	PARI/O	1.2	8.6		7.9	1.7	6.6		
tpd [†]	Both modes	CLK	PARI/O	1	6.8		5.2	1.3	4.5	ns	
tpd	Both modes	MODE	Y	1	5.9		5.8	1.3	4.9	ns	
^t PLH	Desister mode	CLK	Y	1	6.1		5.5	1.2	4.8	20	
^t PHL	Register mode	CLK		1	5.9		4.9	1.2	4.6	ns	
	Both modes	OE	Y	1.1	6.5		6.4	1.4	5.4	20	
ten	Both modes	PAROE	PARI/O	1	5.6		6	1	4.8	ns	
	Dette see de s	OE	Y	1	6.4		5.2	1.7	5		
^t dis	Both modes	PAROE	PARI/O	1	3.2		3.8	1.2	3.8	ns	
^t PLH	Dath madas		VEDD	1	3.6		4.2	1.9	4		
^t PHL	Both modes	ŌĒ	YERR	1.2	5.1		4.9	1.5	4.2	ns	

[†] See Figures 2 and 5 for the load specification.



simultaneous switching characteristics (see Figures 3 and 6)[†]

PA	PARAMETER (INPUT) (O		TO (OUTPUT)	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	
^t PLH	Pogistor mode	CLK	V	1.8	6.5		6.1	1.8	5	-
^t PHL	Register mode	ULK	r i	1.4	5.9		5.1	1.7	4.5	ns

[†] All outputs switching

operating characteristics for buffer mode, T_A = 25°C

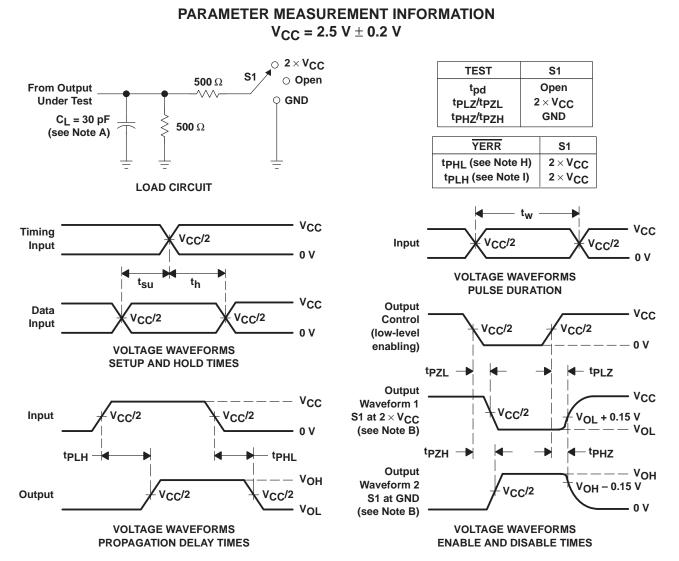
PARAMETER			TEST C	ONDITIONS	$\begin{array}{c} v_{CC} = 2.5 \ V \\ \pm \ 0.2 \ V \end{array} \begin{array}{c} v_{CC} = 3.3 \ V \\ \pm \ 0.3 \ V \end{array}$		UNIT	
					TYP	TYP		
	Power dissipation capacitance	Outputs enabled	C: = 0	f = 10 MHz	57.5	65	рF	
C _{pd}	Power dissipation capacitance	Outputs disabled	$C_{L} = 0,$		15	17.5	ΡF	

operating characteristics for register mode, T_{A} = 25 $^{\circ}C$

	PARAMETER			TEST CONDITIONS		V _{CC} = 3.3 V ± 0.3 V	UNIT
					TYP	TYP	
	Dower dissipation consoitance	Outputs enabled	C 0	f _ 10 MHz	57	87.5	ъF
C _{pd}	Power dissipation capacitance	Outputs disabled	C _L = 0,	f = 10 MHz	16.5	34	pF



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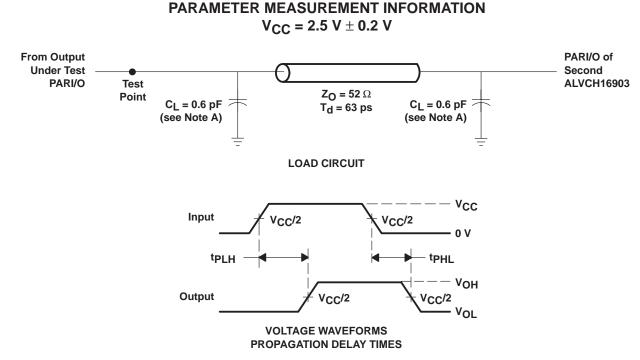


- NOTES: A. Cl includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.

 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. tPLH and tPHL are the same as tpd.
 - H. t_{PHL} is measured at V_{CC}/2.
 - I. tpLH is measured at VOL + 0.15 V.

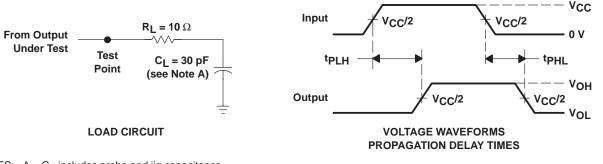
Figure 1. Load Circuit and Voltage Waveforms





- NOTES: A. CL includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
 - C. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

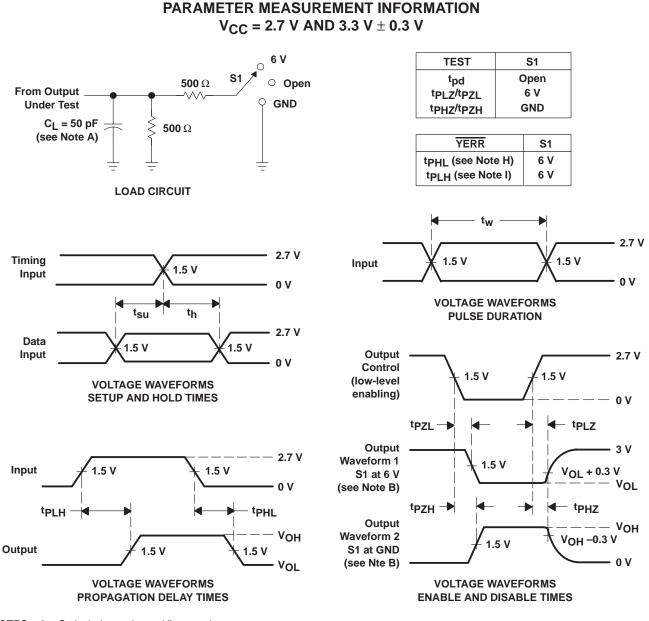


- NOTES: A. C_L includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z₀ = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.

Figure 3. Load Circuit and Voltage Waveforms



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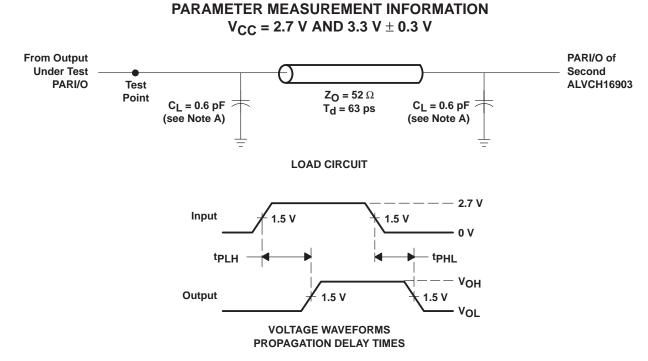


NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control. C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns. t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl $_7$ and tpH $_7$ are the same as t_{dis}.
- F. tpzL and tpzH are the same as ten.
- G. tPLH and tPHL are the same as tpd.
- H. tPHL is measured at 1.5 V.
- I. tpl H is measured at VOI + 0.3 V.

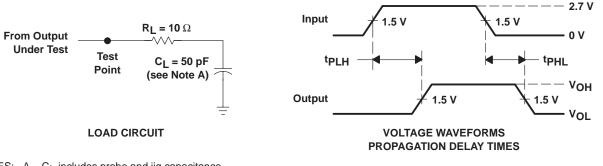






- NOTES: A. CL includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω, t_f \leq 2.5 ns, t_f \leq 2.5 ns.
 - C. tpLH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms



NOTES: A. $\ensuremath{\mathsf{C}}_L$ includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

Figure 6. Load Circuit and Voltage Waveforms



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